



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE5012B E1000		<b>Issued</b>		24. January 2018		
<b>MA#</b>		MA001191324						
<b>Package</b>		PG-DSO-8-16		<b>Weight*</b>		83.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.535	4.23	4.23	42317	42317
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8587	
wire	non noble metal	copper	7440-50-8	29.121	34.87	35.78	348653	357776
	noble metal	gold	7440-57-5	0.129	0.15	0.15	1539	1539
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1125
plastics	plastics	epoxy resin	-	4.321	5.17		51731	
	inorganic material	silicondioxide	60676-86-0	42.551	50.95	56.23	509441	562297
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9744	9744
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7785	7785
glue	plastics	acrylic resin	-	0.341	0.41		4079	
	noble metal	silver	7440-22-4	1.208	1.45	1.86	14463	18542
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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